GP1S53V/GP1S58V

Compact Photointerrupter

■ Features

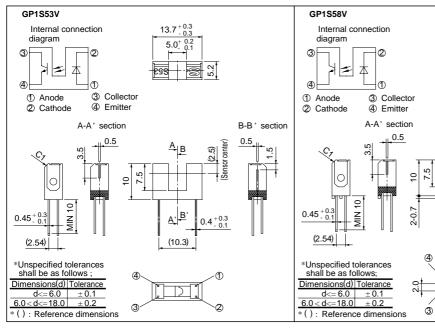
- 1. Compact type
- 2. High sensing accuracy (Slit width: 0.5mm)
- 3. PWB direct mounting type
- 4. With positioning pin (**GP1S58V**)

■ Outline Dimensions

■ Applications

- 1. OA equipment, such as FDDs, printers, facsimiles
- 2. VCRs
- 3. Optoelectronic switches

(Unit: mm)



GP1S58V
Internal connection diagram 3
① Anode ③ Collector ② Cathode ④ Emitter
A-A' section B-B' section 0.5 0.5 0.5 0.4 0.45 0.4 0.4 0.
*Unspecified tolerances shall be as follows;

■ Absolute Maximum Ratings (Ta= 25°C)

	Parameter	Symbol	ymbol Rating		
Input	Forward current	I_F	50	mA	
	*1Peak forward current	I _{FM}	1	A	
	Reverse voltage	V _R	6	V	
	Power dissipation	P	75	mW	
Output	Collector-emitter voltage	V _{CEO}	35	V	
	Emitter-collector voltage	V _{ECO}	6	V	
	Collector current	Ic	20	mA	
	Collector power dissipation	Pc	75	mW	
Operating temperature		T _{opr}	- 25 to + 85	°C	
Storage temperature		T _{stg}	- 40 to + 100	°C	
*2 Soldering temperature		T _{sol}	260	°C	

^{*1} Pulse width <= 100 \mu s, Duty ratio= 0.01

^{*2} For 5 seconds

■ Electro-optical Characteristics

 $(Ta = 25^{\circ}C)$

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit	
Input	Forward voltage		VF	$I_F = 20 \text{mA}$	-	1.25	1.4	V
	Peak forward voltage		V _{FM}	$I_{FM} = 0.5A$	-	3	4	V
	Reverse current		I_R	$V_R = 3V$	-	-	10	μΑ
Output	Collector dark current		I _{CEO}	$V_{\text{CE}} = 20V$	-	1	100	nA
Transfer charac- teristics	Collector Current		Ic	$I_F = 20mA, V_{CE} = 5V$	0.5	-	1.5	mA
	Collector-emitter saturation voltage		V _{CE(sat)}	$I_F = 40mA$, $I_C = 0.2mA$	-	-	0.4	V
	Response time	Rise time	$t_{\rm r}$	$V_{CE} = 2V$, $I_{C} = 2mA$	-	3	15	μs
		Fall time	t_{f}	$R_L = 100 \Omega$	-	4	20	μs

Fig. 1 Forward Current vs. Ambient Temperature

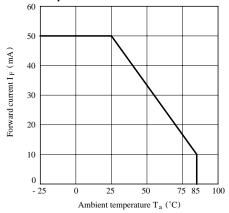


Fig. 3 Peak Forward Current vs. Duty Ratio

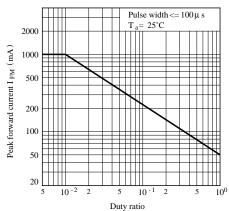


Fig. 2 Collector Power Dissipation vs.
Ambient Temperature

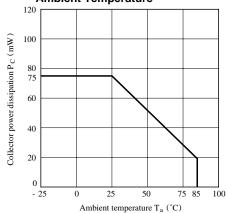


Fig. 4 Forward Current vs. Forward Voltage

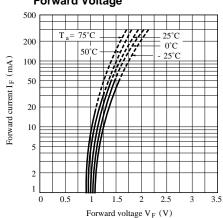


Fig. 5 Collector Current vs. Forward Current

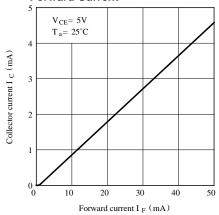


Fig. 7 Collector Current vs.
Ambient Temperature

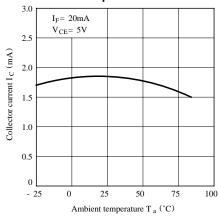


Fig. 9 Response Time vs. Load Resistance

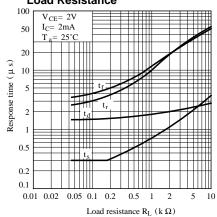


Fig.6 Collector Current vs.
Collector-emitter Voltage

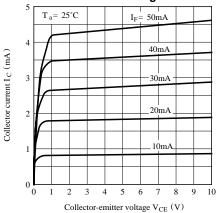
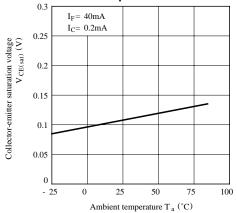


Fig. 8 Collector-emitter Saturation Voltage vs. Ambient Temperature



Test Circuit for Response Time

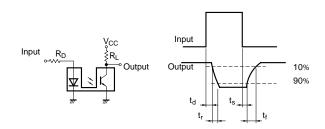


Fig.10 Frequency Response

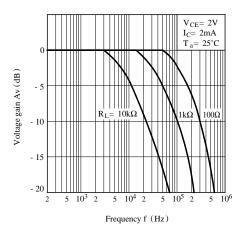


Fig.12 Relative Collector Current vs. Shield Distance (1)

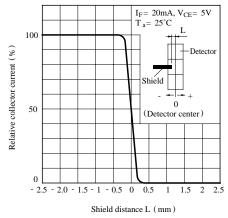


Fig.11 Collector Dark Current vs.
Ambient Temperature

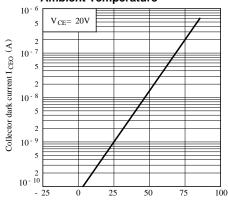
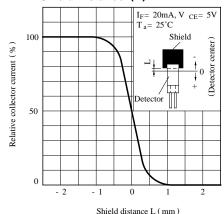


Fig.13 Relative Collector Current vs. Shield Distance (2)

Ambient temperature T a (°C)



■ Precautions for Use

- (1) In case of cleaning, use only the following type of cleaning solvent. Ethyl alcohol, methyl alcohol, Isopropyl alcohol
- (2) As for other general cautions, refer to the chapter "Precautions for Use".

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